

Description

The DMG7408SFG uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 30V I_{D} = 20 A$

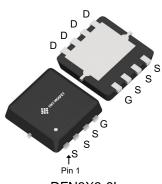
 $R_{DS(ON)}$ < 20m Ω @ V_{GS} =10V

Application

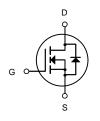
Battery protection

Load switch

Uninterruptible power supply



DFN3X3-8L (PowerDI3333-8)



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
DMG7408SFG	DFN3X3-8L(PowerDI3333-8)	HXY MOSFET	5000

Absolute Maximum Ratings (T_c =25 ℃ unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	30	V
VGS	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	20	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	8	А
IDM	Pulsed Drain Current ²	38	А
EAS	Single Pulse Avalanche Energy ³	28	mJ
IAS	Avalanche Current	13.8	А
P _D @T _C =25°C	Total Power Dissipation⁴	5.5	W
TSTG	Storage Temperature Range	-55 to 175	°C
TJ	Operating Junction Temperature Range	-55 to 175	°C
R₀JC	Thermal Resistance Junction-Case ¹	36	°C/W



Electrical Characteristics (T_J=25 °C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} = 0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V_{DS} =0V, V_{GS} = ±20V	_	-	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.5	2.5	V
Ь	Static Drain-Source on-Resistance	V _{GS} =10V, I _D =5A	-	15	20	mΩ
R _{DS(on)}		V _{GS} =4.5V, I _D =3A	-	21	29	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1.0MHz	-	490	-	pF
Coss	Output Capacitance		_	79	-	pF
C _{rss}	Reverse Transfer Capacitance		_	61	-	pF
Qg	Total Gate Charge	V _{DS} =15V, I _D =5.8A, V _{GS} =10V	-	10	-	nC
Q _{gs}	Gate-Source Charge		-	1.7	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	2.5	-	nC
t _{d(on)}	Turn-on Delay Time		-	6	-	ns
t _r	Turn-on Rise Time	V _{DS} =15V, I _D =3A,	-	15	-	ns
t _{d(off)}	Turn-off Delay Time	V_{GS} =10V, R_{REN} =3 Ω	_	17	-	ns
t _f	Turn-off Fall Time		-	17	-	ns
Is	Maximum Continuous Drain to Source Diode Forward Current		-	-	9	Α
I _{SM}	Maximum Pulsed Drain to Source Dio	num Pulsed Drain to Source Diode Forward Current		-	36	Α
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =9A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	7	-	ns
Qrr	Body Diode Reverse Recovery Charge	I _F =5A, dI/dt=100A/µs	-	2	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

- 2. EAS condition : T_J =25°C, V_{DD} =15V, V_G =10V,L=0.5mH,Rg=25 Ω , I_{AS} =6A
- 3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



Typical Performance Characteristics

Figure1: Output Characteristics

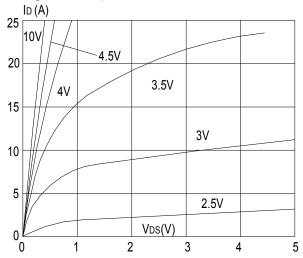


Figure 3:On-resistance vs. Drain Current

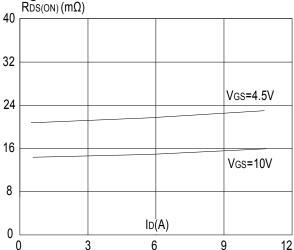


Figure 5: Gate Charge Characteristics

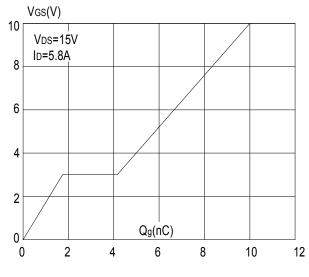


Figure 2: Typical Transfer Characteristics

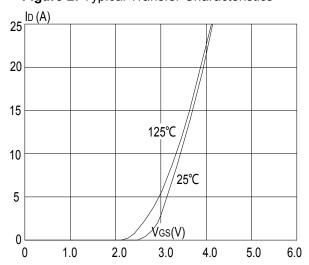


Figure 4: Body Diode Characteristics

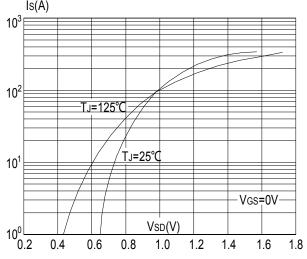


Figure 6: Capacitance Characteristics

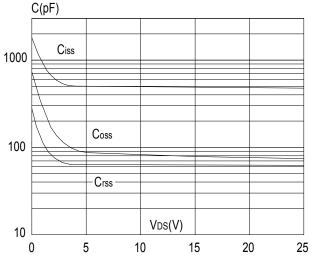




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

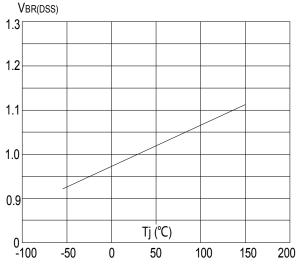


Figure 9: Maximum Safe Operating Area

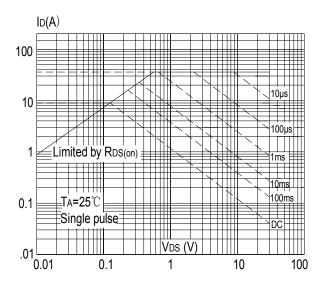


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient ZthJ-A($^{\circ}$ C/W)

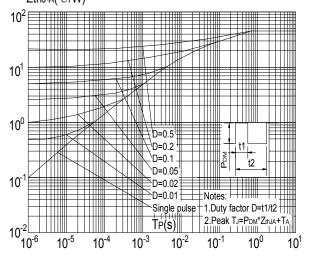


Figure 8: Normalized on Resistance vs. Junction Temperature

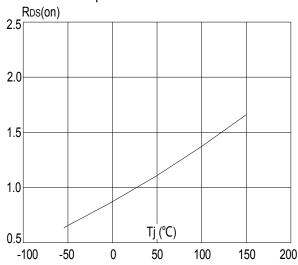
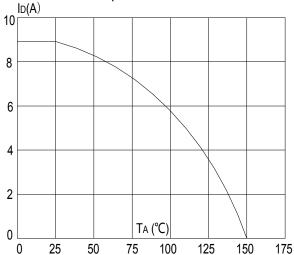
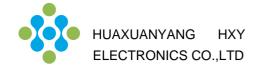


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature





Test Circuit

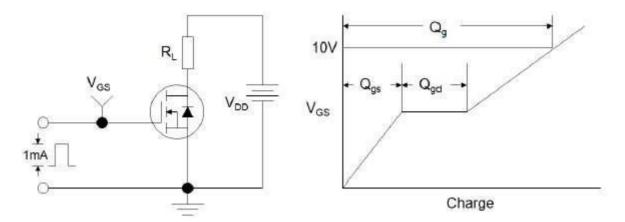


Figure1:Gate Charge Test Circuit & Waveform

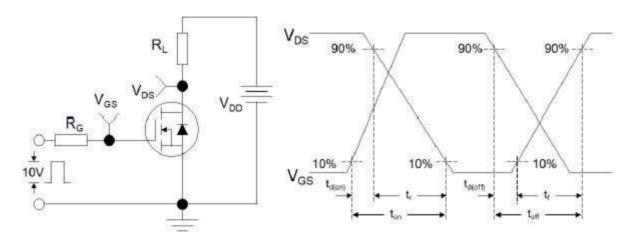


Figure 2: Resistive Switching Test Circuit & Waveforms

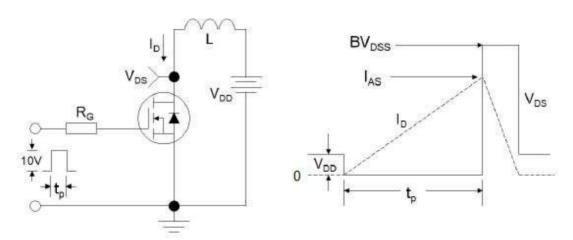
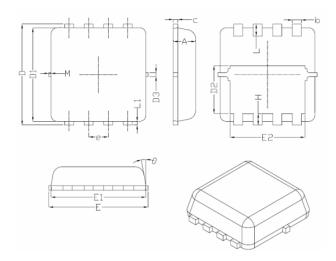


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms



DFN3X3-8L(PowerDI3333-8) Package Information



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	0.70	0.75	0.80
b	0.25	0.30	0.35
С	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.48	1.58	1.68
D3	-	0.13	-
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
е	0.65BSC		
Н	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	-	0.13	-
M	*	*	0.15
θ		10 [°]	12 [°]



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